

Appl. No. 10/806,590  
Amdt. Dated April 13, 2007  
Reply to Office Action of January 18, 2007

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**Amendments to Prosecution of the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

Claim 1 (currently amended): A mold fabricating method, comprising:

providing a base plate;

forming cylindrical recesses in the base plate using a series of photo mask processes, each photo mask process forming a corresponding set of cylindrical recesses, each following photo mask process forming a further respective cylindrical recess in each previously formed cylindrical recess, each following photo mask process yielding a corresponding set of the further cylindrical recesses with a respective smaller diameter than the previously formed set of the cylindrical recesses, the series of photo mask processes including enough such photo mask processes so as to yield a plurality of respectively approximately half sphere-shaped recesses.

Claim 2 (cancelled).

Claim 3 (currently amended): The method as claimed in claim [[2]] 1, wherein each photo mask process comprises following the steps:

~~covering a resist film on the base plate~~ with a resist film;

forming a mask;

~~forming a pattern in the resist film by radiation exposure through the mask;~~

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etching the base plate by a chemical method to get cylindrical recesses; and

cleaning the remnant resist film and other foreign particles from the base plate.

Claim 4 (currently amended): The method as claimed in claim ~~[[3]]~~ 1, wherein an aligning step is performed prior to each given ~~between two~~ photo mask ~~step~~ process.

Claim 5 (currently amended): The method as claimed in claim ~~[[4]]~~ 3, wherein the base plate is made of nickel or nickel alloy.

Claim 6 (currently amended): The method as claimed in claim ~~[[5]]~~ 3, wherein the resist film comprises a resist and an organic polymer.

Claim 7 (original): The method as claimed in claim 6, wherein the resist film adopts positive acting resist.

Claim 8 (original): The method as claimed in claim 6, wherein the resist film adopts negative-acting resist.

Claim 9 (currently amended): The method as claimed in claim 1, wherein each photo mask process ~~formed~~ forms narrower and deeper cylindrical recesses in the same position of the ~~former~~ previous photo mask process in the base plate.

Claim 10 (currently amended): The method as claimed in claim 9, wherein each photo mask process comprises following the steps:

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~~covering a resist film on the base plate with a resist film;~~  
forming a mask;  
forming a pattern in the resist film by radiation exposure through the mask;  
etching the base plate by chemical method to get cylindrical recesses;  
and  
cleaning the remnant resist film and other foreign particles.

Claim 11 (currently amended): The method as claimed in claim 10, wherein an aligning step is performed prior to each given ~~between two~~ photo mask ~~step~~ process.

Claim 12 (currently amended): The method as claimed in claim ~~[[11]]~~ 10, wherein the base plate is made of nickel or nickel alloy.

Claim 13 (currently amended): The method as claimed in claim ~~[[12]]~~ 10, wherein the resist film comprises a resist and an organic polymer.

Claim 14 (original): The method as claimed in claim 13, wherein the resist film adopts positive acting resist.

Claim 15 (original): The method as claimed in claim 14, wherein the resist film adopts negative-acting resist.